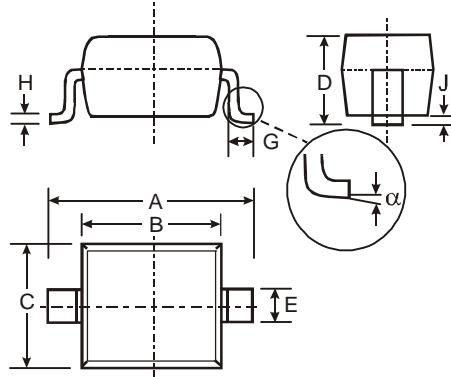


**Features**

- Low Forward Voltage Drop
- Guard Ring Die Construction for Transient Protection
- Ideal for low logic level applications
- Low Capacitance
- **Lead, Halogen and Antimony Free, RoHS Compliant "Green" Device (Notes 3 and 4)**

**Mechanical Data**

- Case: SOD-323
- Case Material: Molded Plastic. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020C
- Leads: Solderable per MIL-STD-202, Method 208
- Lead Free Plating (Matte Tin Finish annealed over Alloy 42 leadframe).
- Polarity: Cathode Band
- Marking: See Page 3
- Type Code: SG
- Weight: 0.004 grams (approximate)



SOD-323		
Dim	Min	Max
A	2.30	2.70
B	1.60	1.80
C	1.20	1.40
D	1.05 Typical	
E	0.25	0.35
G	0.20	0.40
H	0.10	0.15
J	0.05 Typical	
α	0°	8°
All Dimensions in mm		

**Maximum Ratings** @T<sub>A</sub> = 25°C unless otherwise specified

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage	V <sub>RRM</sub>	30	V
Working Peak Reverse Voltage	V <sub>RWM</sub>		
DC Blocking Voltage	V <sub>R</sub>		
RMS Reverse Voltage	V <sub>R(RMS)</sub>	21	V
Forward Continuous Current (Note 1)	I <sub>FM</sub>	100	mA
Non-Repetitive Peak Forward Surge Current @ t ≤ 10ms	I <sub>FSM</sub>	750	mA
Power Dissipation (Note 1)	P <sub>D</sub>	250	mW
Thermal Resistance, Junction to Ambient Air (Note 1)	R <sub>θJA</sub>	500	°C/W
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-65 to 150	°C

**Electrical Characteristics** @T<sub>A</sub> = 25°C unless otherwise specified

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 2)	V <sub>(BR)R</sub>	30	—	—	V	I <sub>R</sub> = 100μA
Forward Voltage Drop	V <sub>FM</sub>	—	300	—	mV	@ I <sub>F</sub> = 2.0mA
			360	—		@ I <sub>F</sub> = 15mA
			470	550		@ I <sub>F</sub> = 50mA
			580	800		@ I <sub>F</sub> = 100mA
Peak Reverse Current (Note 2)	I <sub>RM</sub>	—	—	1.0	μA	V <sub>R</sub> = 25V
Total Capacitance	C <sub>T</sub>	—	7	—	pF	V <sub>R</sub> = 10V f = 1.0 MHz

- Notes:
1. Part mounted on FR-4 PC board with recommended pad layout, which can be found on our website at <http://www.diodes.com/datasheets/ap02001.pdf>.
  2. Short duration pulse test used to minimize self-heating effect.
  3. No purposefully added lead. Halogen and Antimony Free.
  4. Product manufactured with Data Code V9 (week 33, 2008) and newer are built with Green Molding Compound. Product manufactured prior to Date Code V9 are built with Non-Green Molding Compound and may contain Halogens or Sb<sub>2</sub>O<sub>3</sub> Fire Retardants.

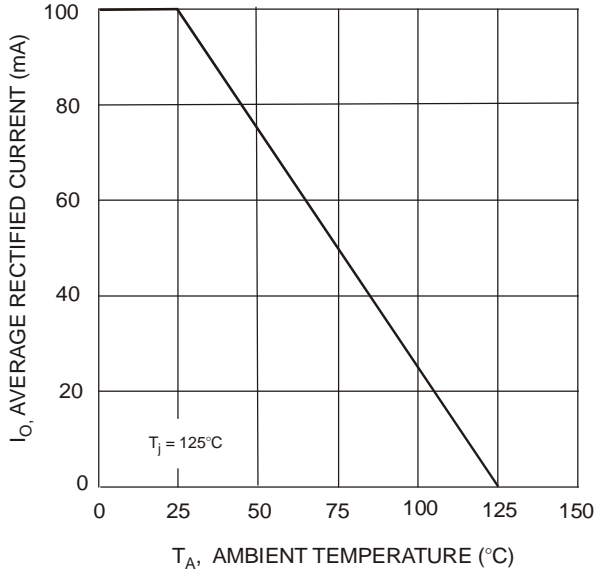


Fig. 1 Forward Current Derating Curve

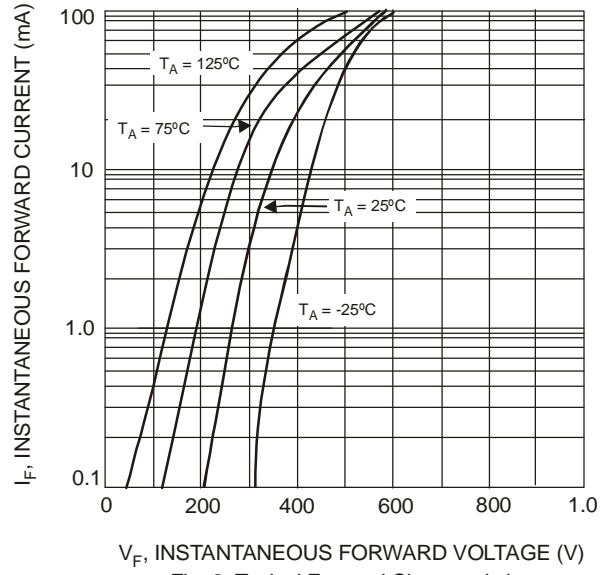


Fig. 2 Typical Forward Characteristics

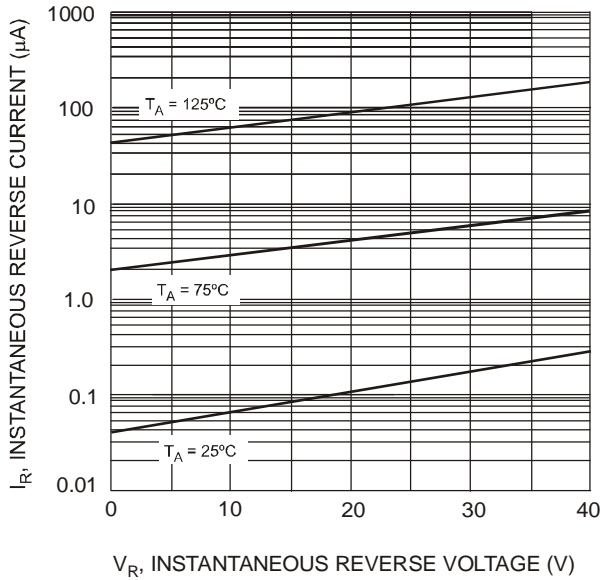


Fig. 3 Typical Reverse Characteristics

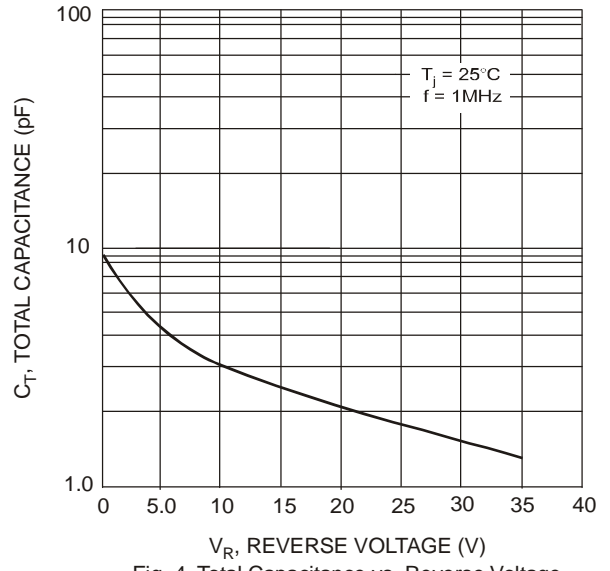


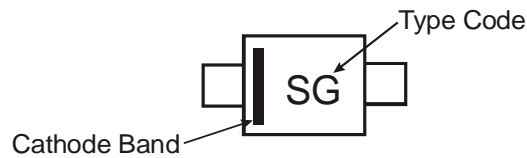
Fig. 4 Total Capacitance vs. Reverse Voltage

**Ordering Information** (Note 5)

Device	Packaging	Shipping
SD107WS-7-F	SOD-323	3000/Tape & Reel

Notes: 5. For packaging details, go to our website at <http://www.diodes.com/datasheets/ap02007.pdf>.

**Marking Information**



**IMPORTANT NOTICE**

Diodes Incorporated and its subsidiaries reserve the right to make modifications, enhancements, improvements, corrections or other changes without further notice to any product herein. Diodes Incorporated does not assume any liability arising out of the application or use of any product described herein; neither does it convey any license under its patent rights, nor the rights of others. The user of products in such applications shall assume all risks of such use and will agree to hold Diodes Incorporated and all the companies whose products are represented on our website, harmless against all damages.

**LIFE SUPPORT**

Diodes Incorporated products are not authorized for use as critical components in life support devices or systems without the expressed written approval of the President of Diodes Incorporated.